## ABSTRACT

An Integrated dicing/die bonding film is disclosed. This integrated dicing/die bonding film includes, in the stated order: a first base material layer; a die-bonding film containing electroconductive particles; a pressure-sensitive adhesive layer; and a second base material layer. The first base material layer has a cut portion provided on a surface of the die-bonding film side along an outer edge of the die-bonding film. A maximum value of 30° peeling strength of the die-bonding film with respect to the first base material layer as measured at 25°C is 0.50 N/20 mm or less.

Fig. 1